**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Application of:

Examiner: Not yet assigned

Youngyul KIM

Serial No.: 10/506,558

Art Unit: Not yet assigned

Filed: September 1, 2004

Title: ELECTRODE FOR DRY ETCHING A WAFER

Mail Stop AMENDMENT
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

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37 C.F.R. §§1.97(b)**

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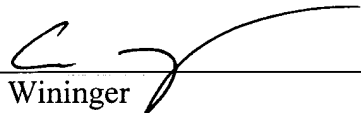
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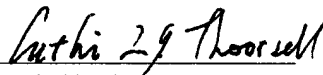
Respectfully submitted,

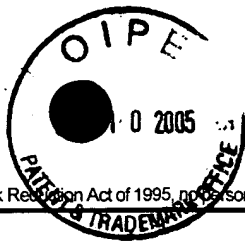
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STATEMENT BY APPLICANT**

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Sheet 1 of 1

Complete if Known

Application Number	10/506,558
Filing Date	September 1, 2004
First Named Inventor	Youngyul KIM
Art Unit	Not yet assigned.
Examiner Name	Not yet assigned.
Attorney Docket Number	61282.00015

NON PATENT LITERATURE DOCUMENTS

Examiner Initials *	Cite No. ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ²
	1.	CHO, Byeong-Ok. <i>et al.</i> , "Angular dependence of the redeposition rates during SiO ₂ etching in a CF ₄ plasma" J. Vac. Sci. Technol. A 19(3) May/Jun 2001, pp. 730-735.	
	2.	LEE, Gyeo-Re <i>et al.</i> "Sidewall-angle effect on the bottom etch profile in SiO ₂ etching using a CF ₄ Plasma" J. Vac. Sci. Technol. B 19(1), Jan/Feb 2001, pp. 172-178.	
	3.	MIN, Jae-Ho, <i>et al.</i> "Reseposition of Etch Products on Sidewalls During SiO ₂ Etching in a Fluorocarbon Plasma. III. Effects of O ₂ Addition to CF ₄ Plasma" J. Vac. Sci. Technol. B21(4) Jul/Aug 2003 American Vacuum Society, pp. 1210-1215.	
	4.	PINTA, R. <i>et al.</i> "Reactive Etching in SF ₆ Gs Mixtures" InP Misfet Technology Vol. 134, No. 1 January 1987, pp. 165-175.	
	5.	ZAROWIN, C.B. "Plasma Etch Anisotropy - Theory and Some Verifying Experiments Relating Ion Transport, Ion Energy, and Etch Profiles" J. Electrochem. Soc.: Solid state Science and Technology, May, 1983, pp. 1144-1152.	

Examiner
SignatureDate
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